

	<h1>Tentative</h1>	<b>DA2S001</b>	
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# DA2S001

Silicon epitaxial planar type

For band switching

Marking Symbol : D1

Package Code : SSMINI2-F5-B

## Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage(DC)	VR	35	V
Forward current (DC)	IF	100	mA
Junction temperature	Tj	150	°C
Operating ambient temperature *1	Topr	-25 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Pin name	1.	Cathode
	2.	Anode

Note: 1. \*1 Maximum ambient temperature during operation.

## Electrical Characteristics Ta = 25 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage(DC)	VF	IF = 100 mA			1.0	V
Reverse current(DC)	IR	VR = 33 V			100	nA
Diode capacitance	CD	VR = 6 V, f = 1 MHz			1.2	pF
Forward dynamic resistance *1	rf	IF = 2 mA, f = 100 MHz			0.85	Ω

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

3. \*1 Measuring instrument:YHP MODEL 4191A RF IMPEDANCE ANALYZER

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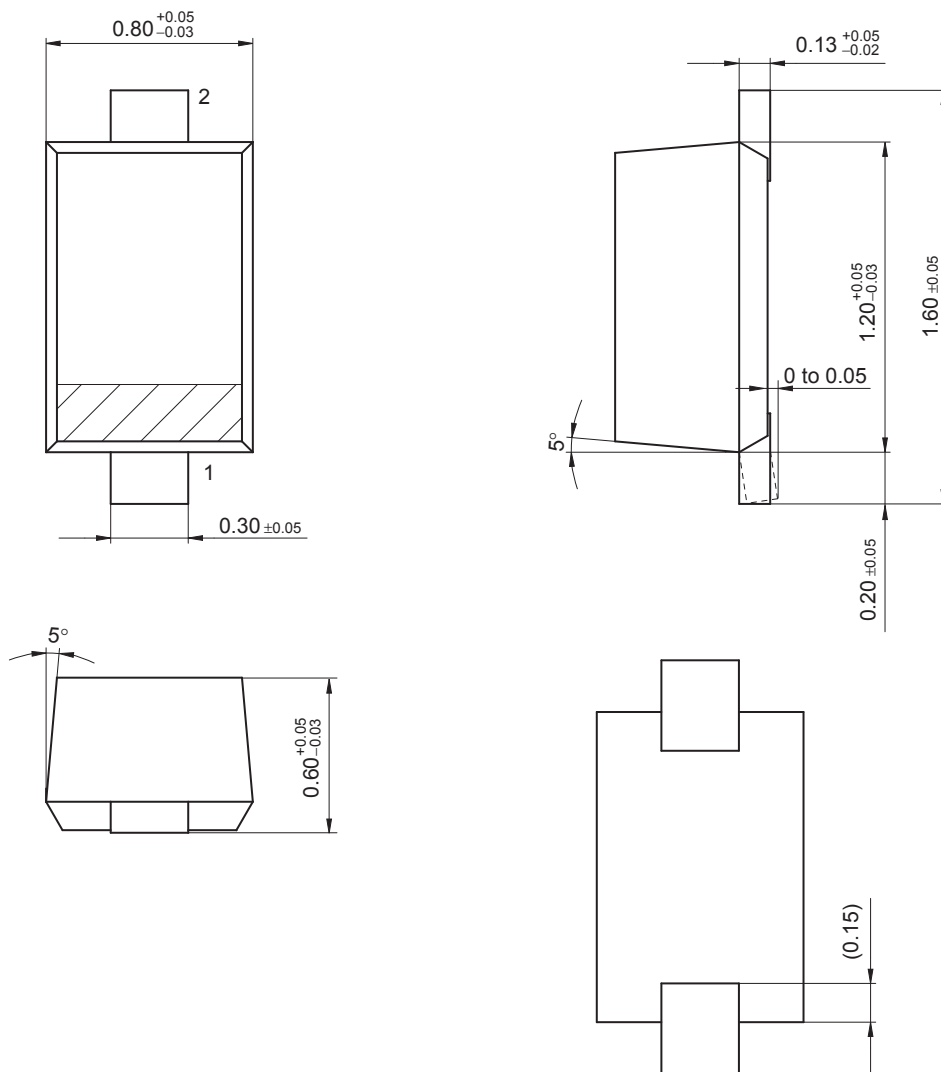
### Packing

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel

2010.1.28	2010.7.29	
Prepared	Revised	

# SSMini2-F5-B

Unit: mm



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